

FIG. 1

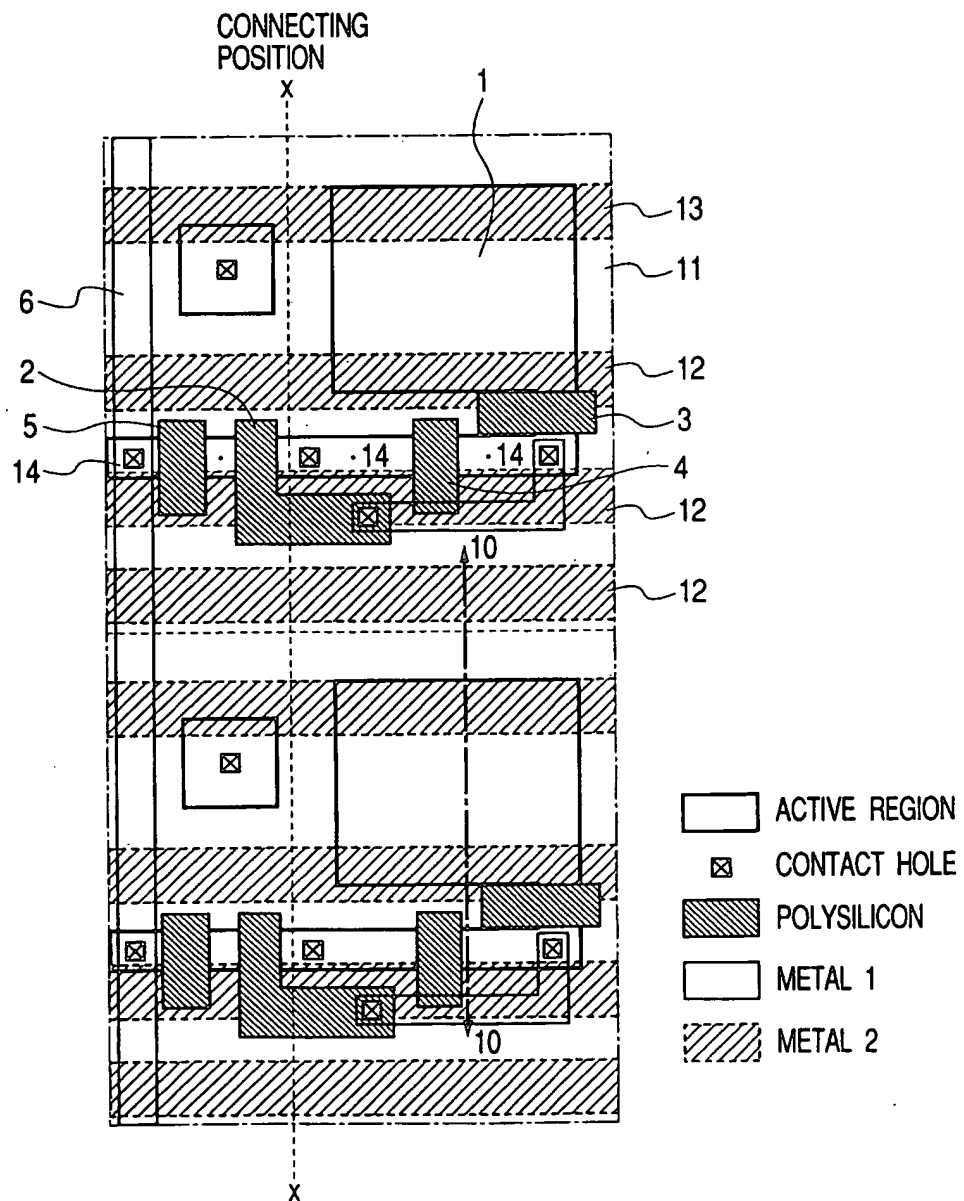


FIG. 2

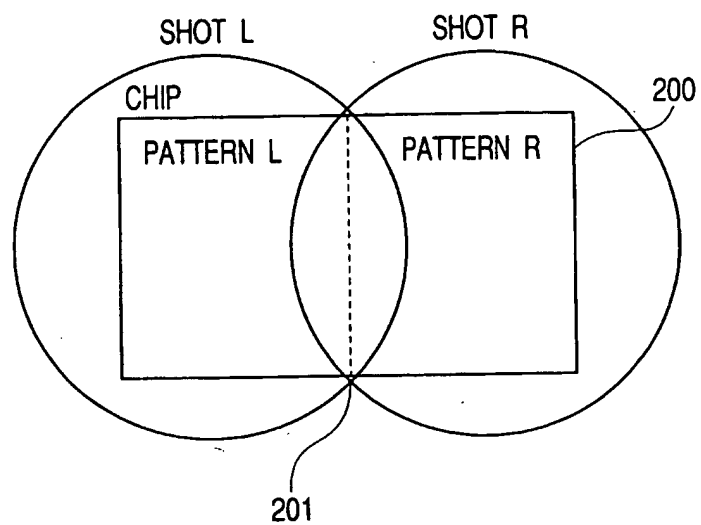


FIG. 3

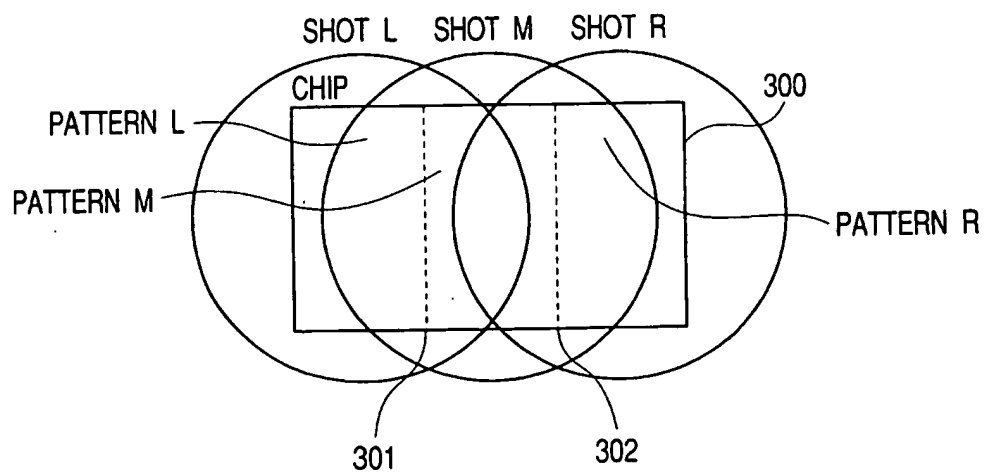


FIG. 4A

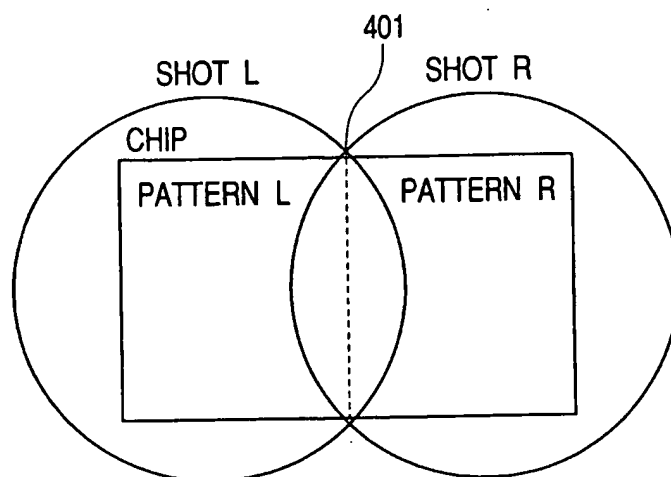


FIG. 4B

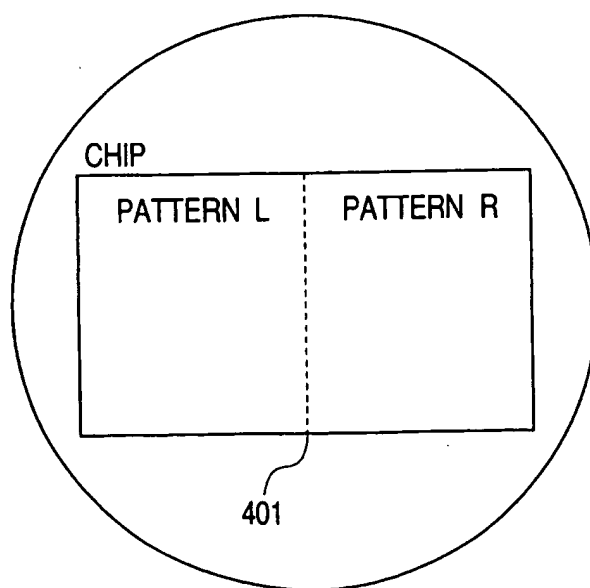


FIG. 5A

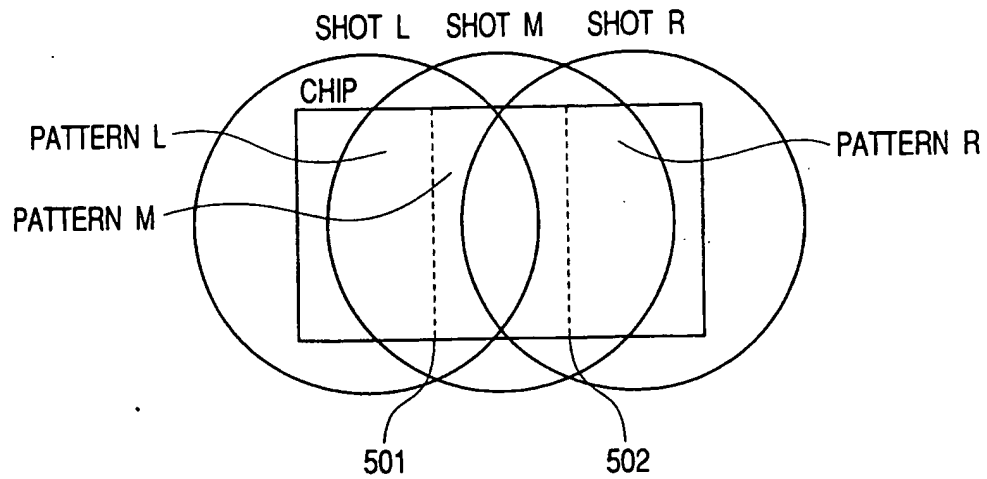


FIG. 5B

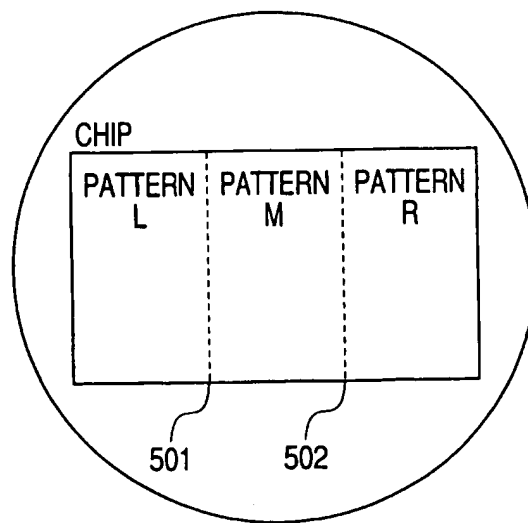


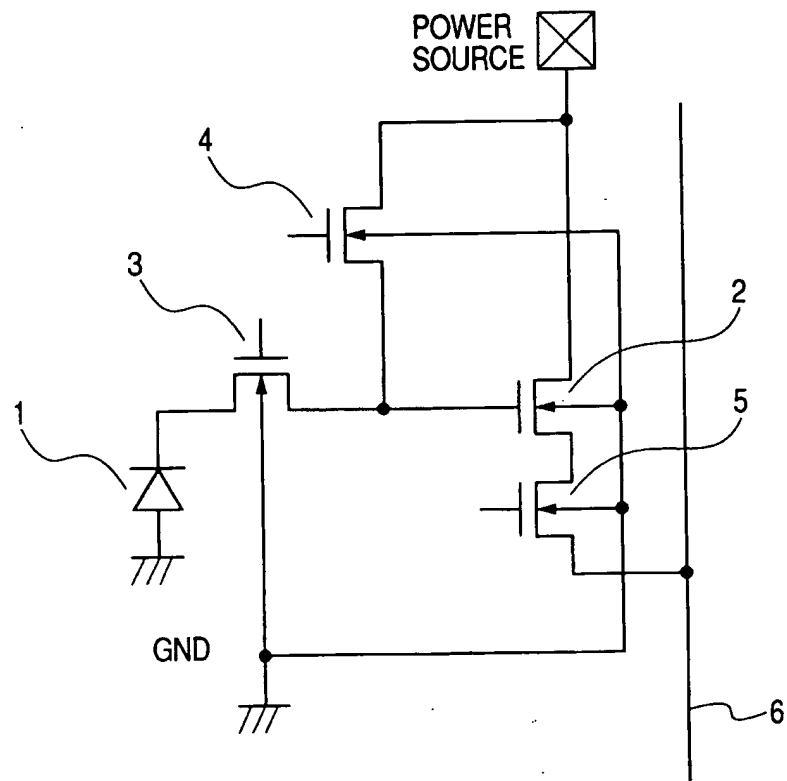
FIG. 6

FIG. 7

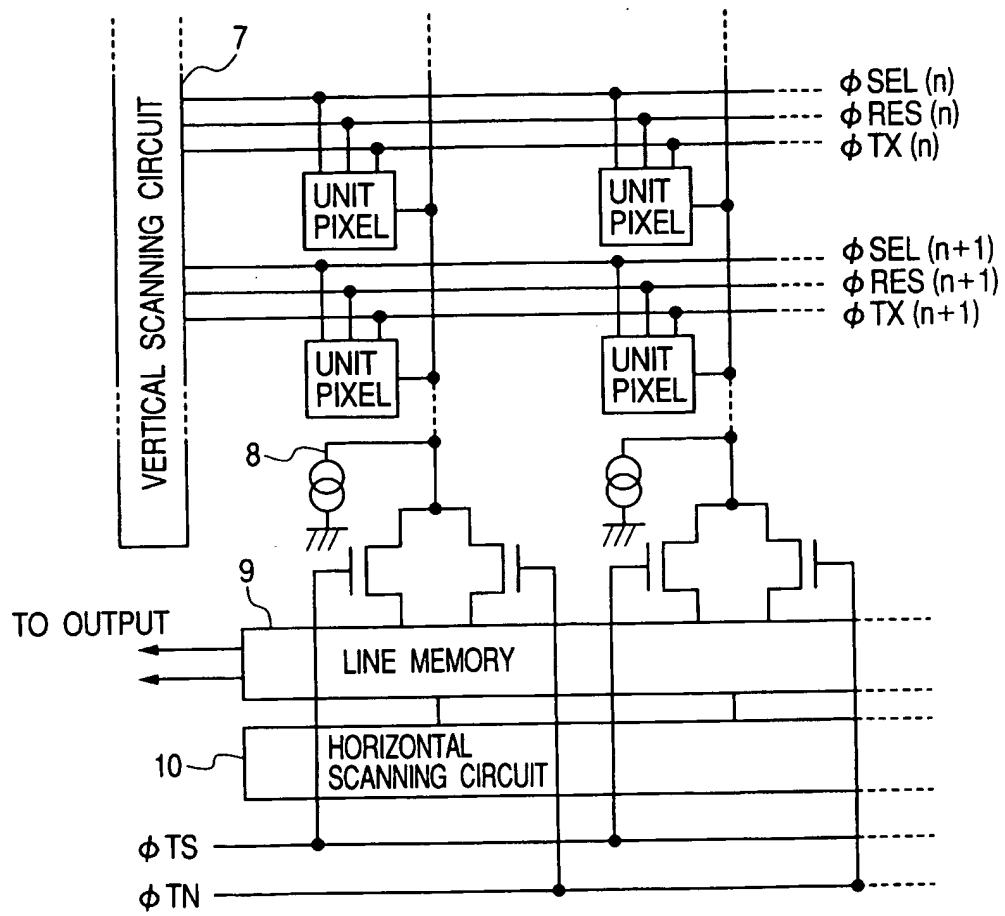


FIG. 8

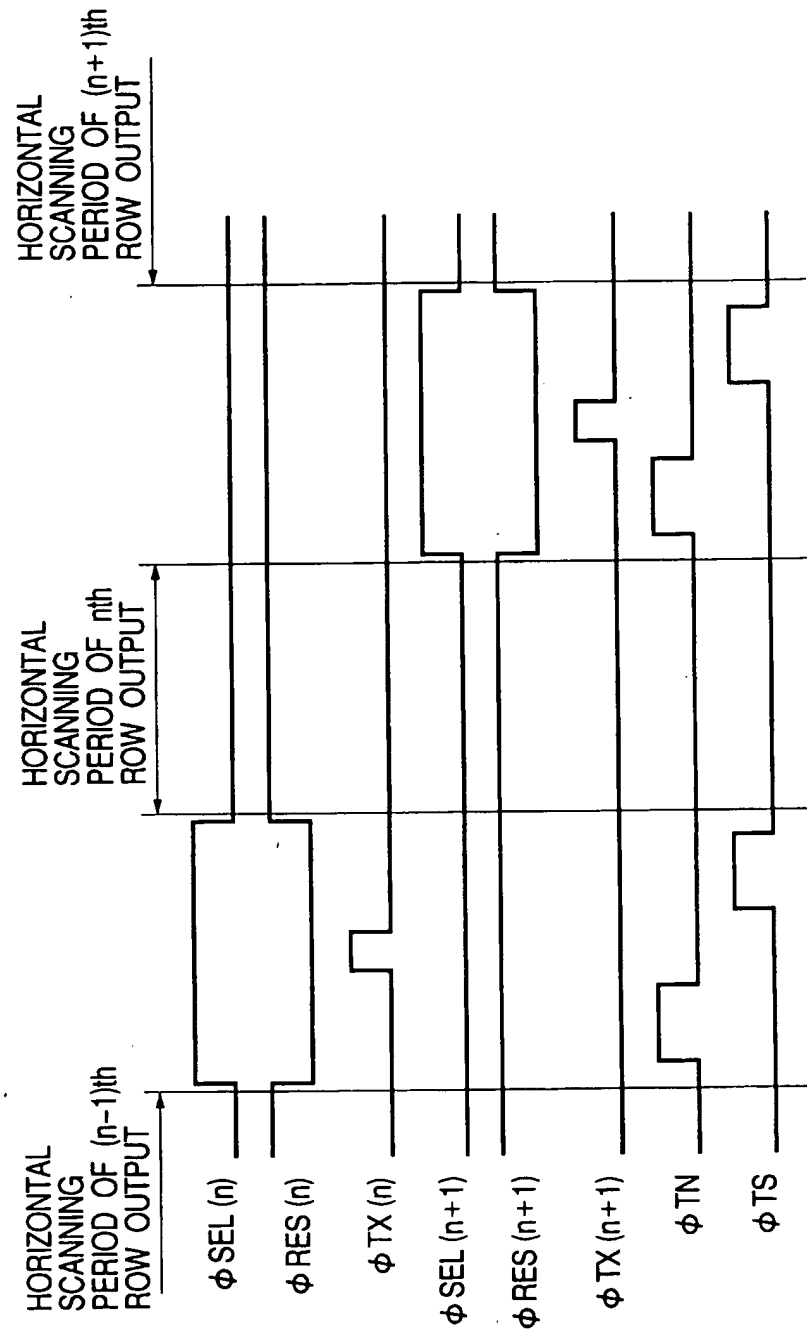


FIG. 9

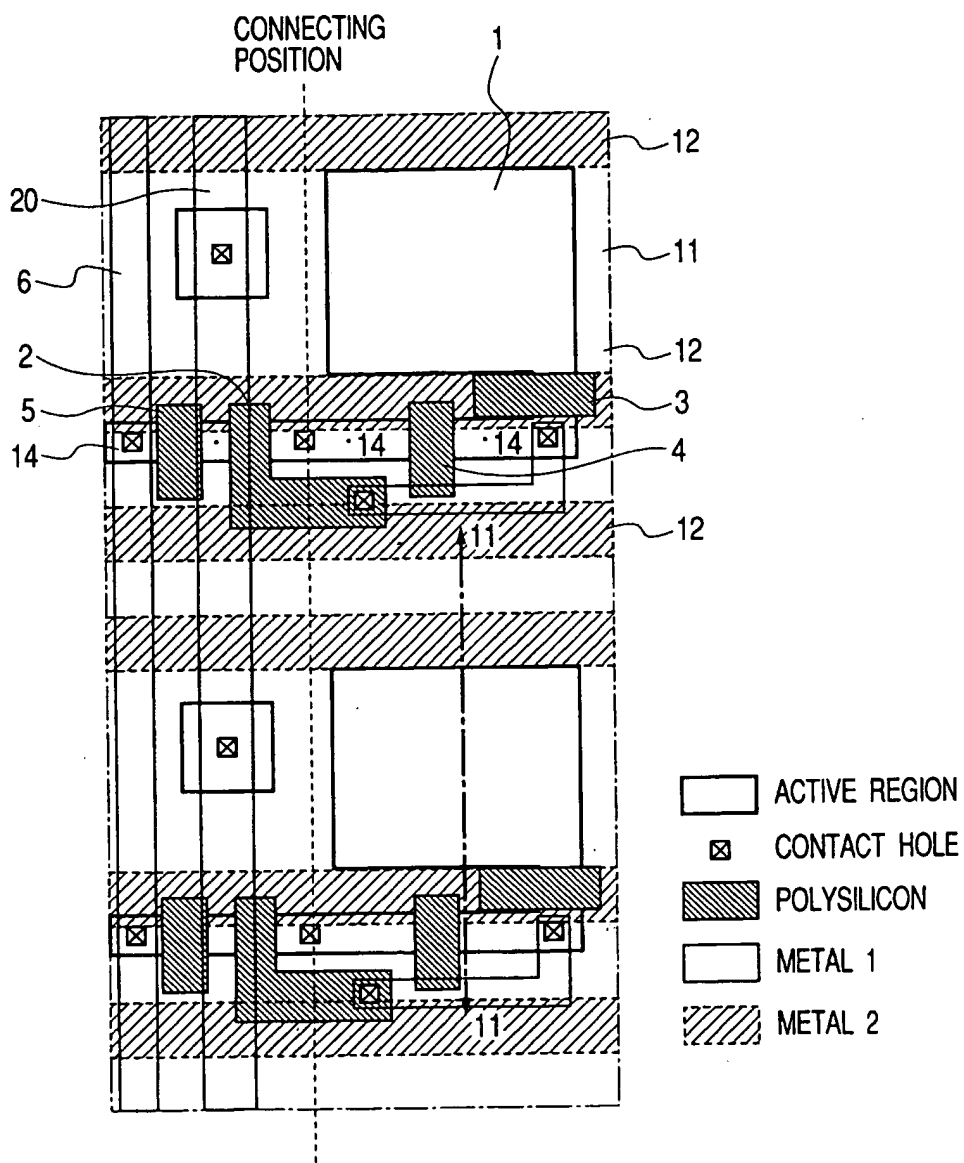


FIG. 10B

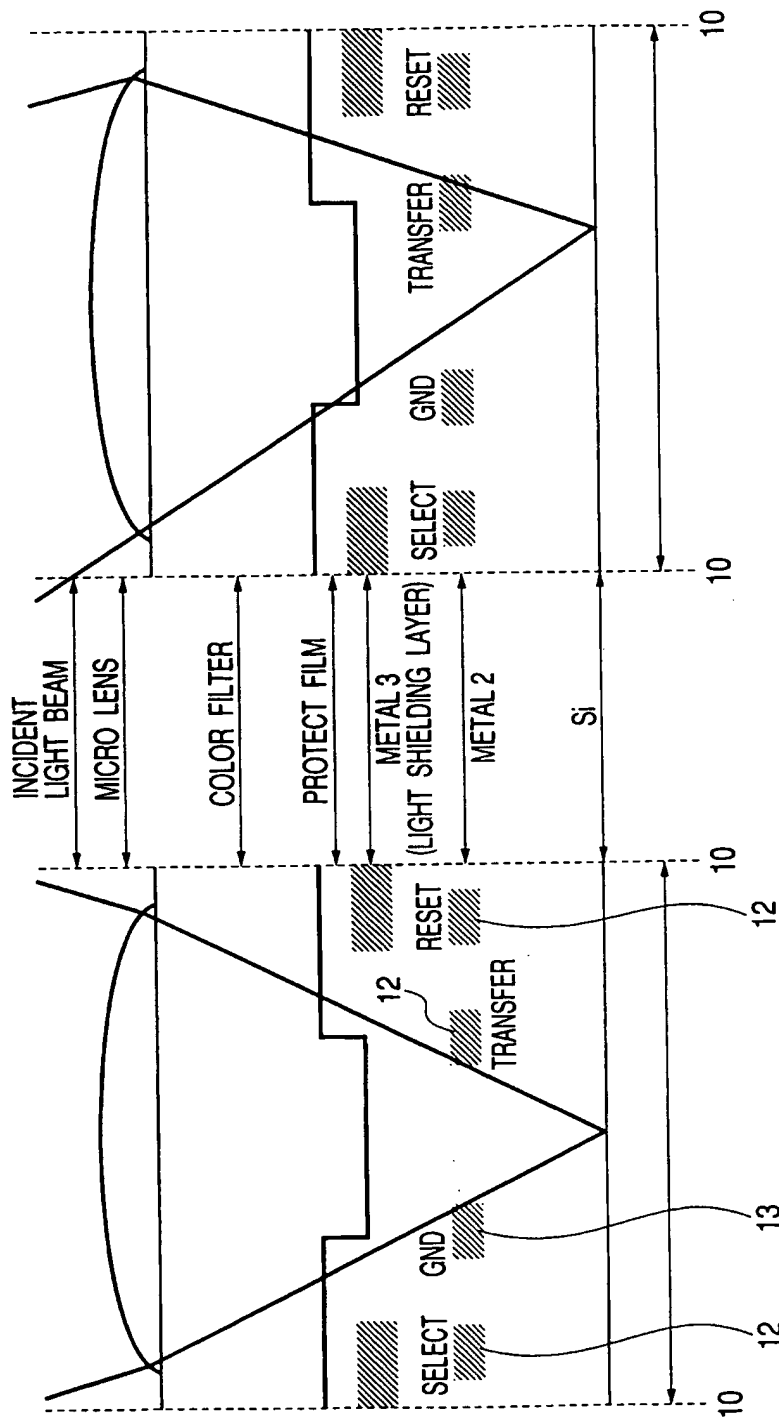


FIG. 10A

FIG. 11B

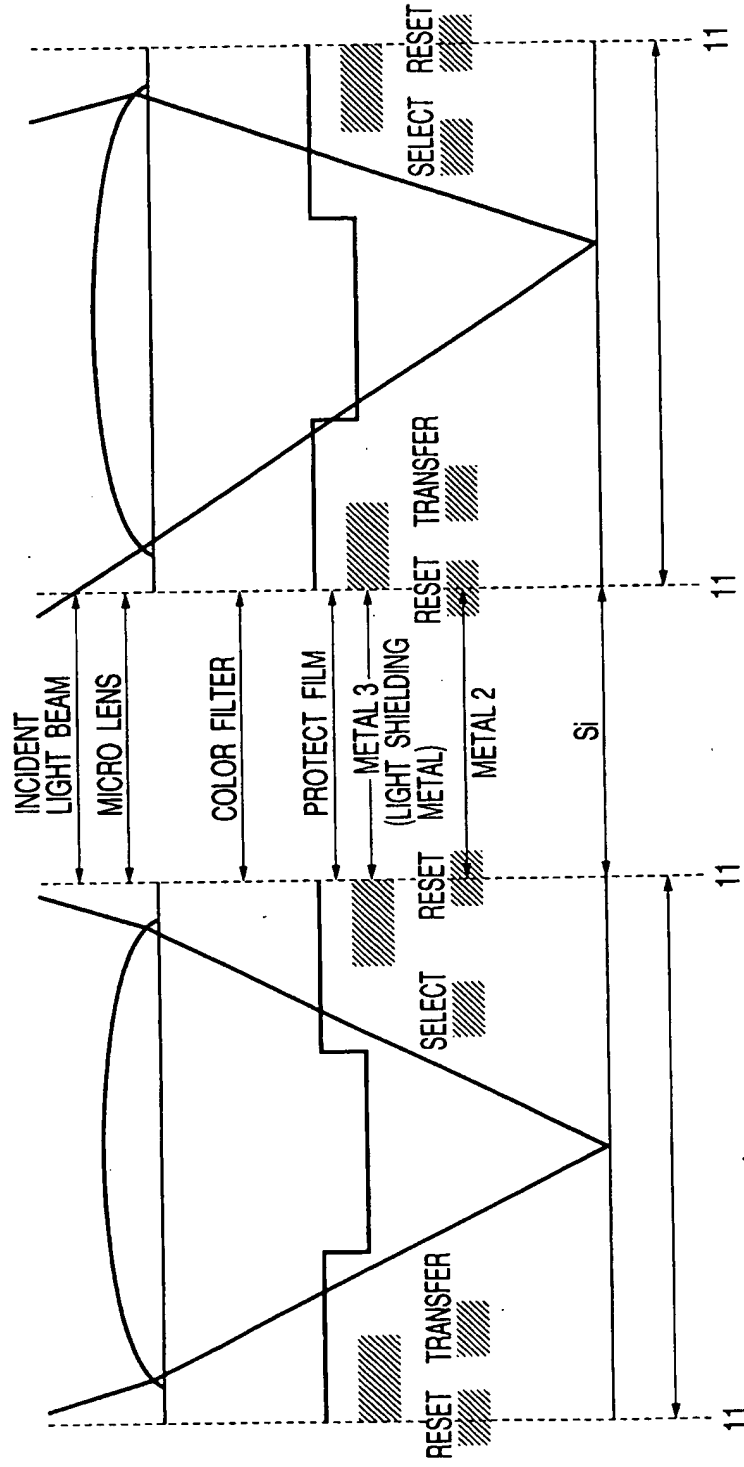


FIG. 11A

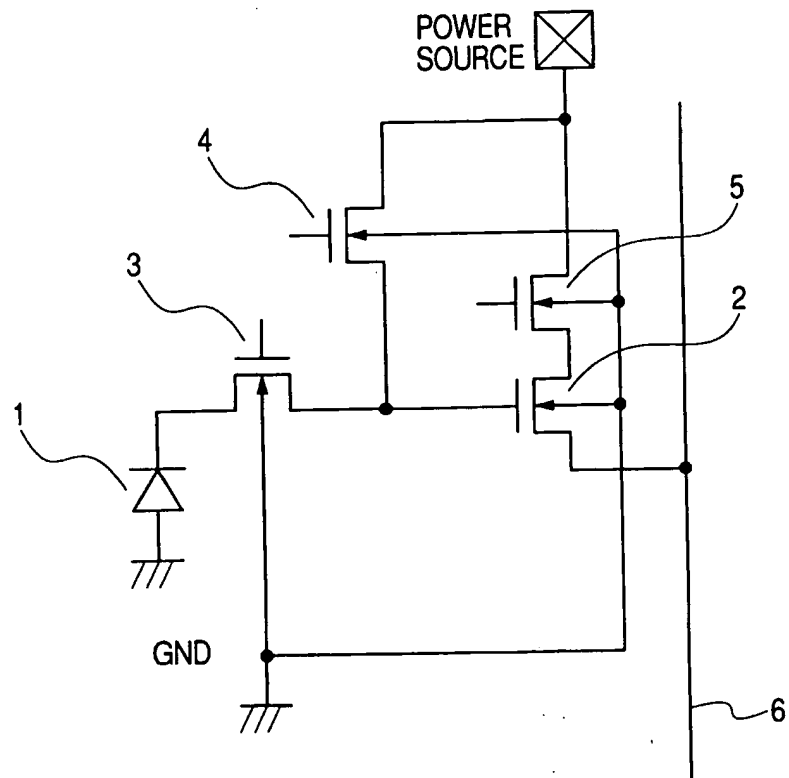
FIG. 12

FIG. 13A

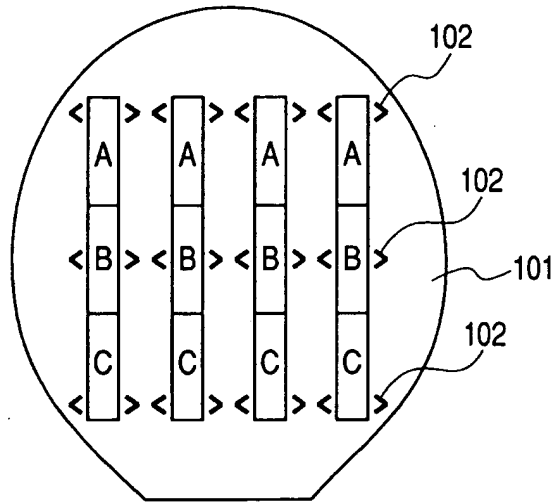


FIG. 13B

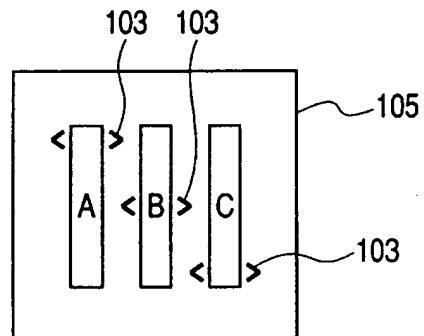


FIG. 13C

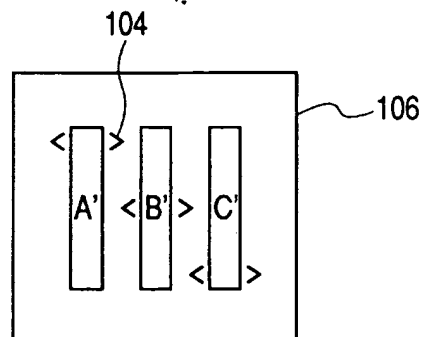
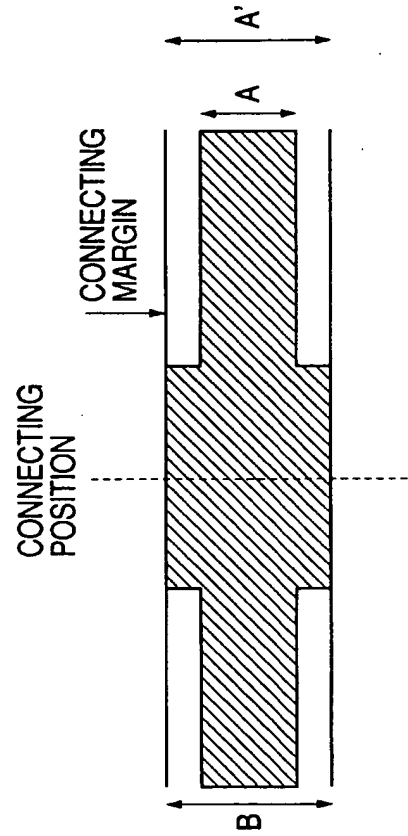


FIG. 14



A : WIRING WIDTH FORMED BY EXPOSURE USING REDUCTION PROJECTING APPARATUS FOR MICROMINIATURE WORKING

A' : WIRING WIDTH FORMED BY DIVISIONAL EXPOSURE (USING CONNECTING MARGIN)

B : WIRING WIDTH FORMED BY BATCH PROCESSING OF EXPOSURE USING REDUCTION PROJECTING APPARATUS OF LARGE EXPOSURE AREA